



503.34403VP2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): MASUDA, et al

Serial No.: 09/421,043

Filed: October 20, 1999

For: PLASMA ETCHING APPARATUS AND PLASMA ETCHING METHOD

Group: 1763

Examiner: L. Alejandro

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

October 19, 2000

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated June 19, 2000. .

IN THE CLAIMS:

Please amend claims 1, 2, 4 and 5 as follows:

1. (amended) A plasma processing apparatus including a vacuum vessel as evacuated by an evacuation system, gas supply means for supplying a processing gas into the vacuum vessel, an electrostatic chucking device for holding thereon a sample to be processed within said vacuum vessel, a lower electrode, a bias power source connected to the lower electrode for

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MW

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